



Customer Information Notification

2015110111

Issue Date: 24-Nov-2015

Effective Date: 26-Dec-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Management Summary

The metal protrusions (connected to the source) at the drain side are relocated to the short side of the package.

Change Category

- | | | | |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process | <input checked="" type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Change position of metal protrusions in SOT1223AC3 / SOT1224AC3 packages

Information Notification

The metal protrusions (connected to the source) at the drain side of the package are relocated to the short side of the package (see also attached document).

The metal protrusion do not have any functionality once NXP package assembly process is finished.

Why do we issue this Information Notification

In a continuous drive to increase the consistency of our products and its applications, the protrusions at the drain side have been put at the side of the devices, which enables the device to be pushed optimum to the drain side, narrowing down further production spread and improving overall performance of customers applications.

Identification of Affected Products

Product identification does not change

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Hans Buis
Position Process Improvement Manager
e-mail address Hans.Buis@NXP.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

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Changed Orderable Part#

BLP8G10S-45PGY

BLP8G10S-45PY